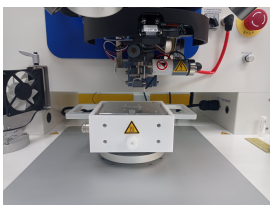
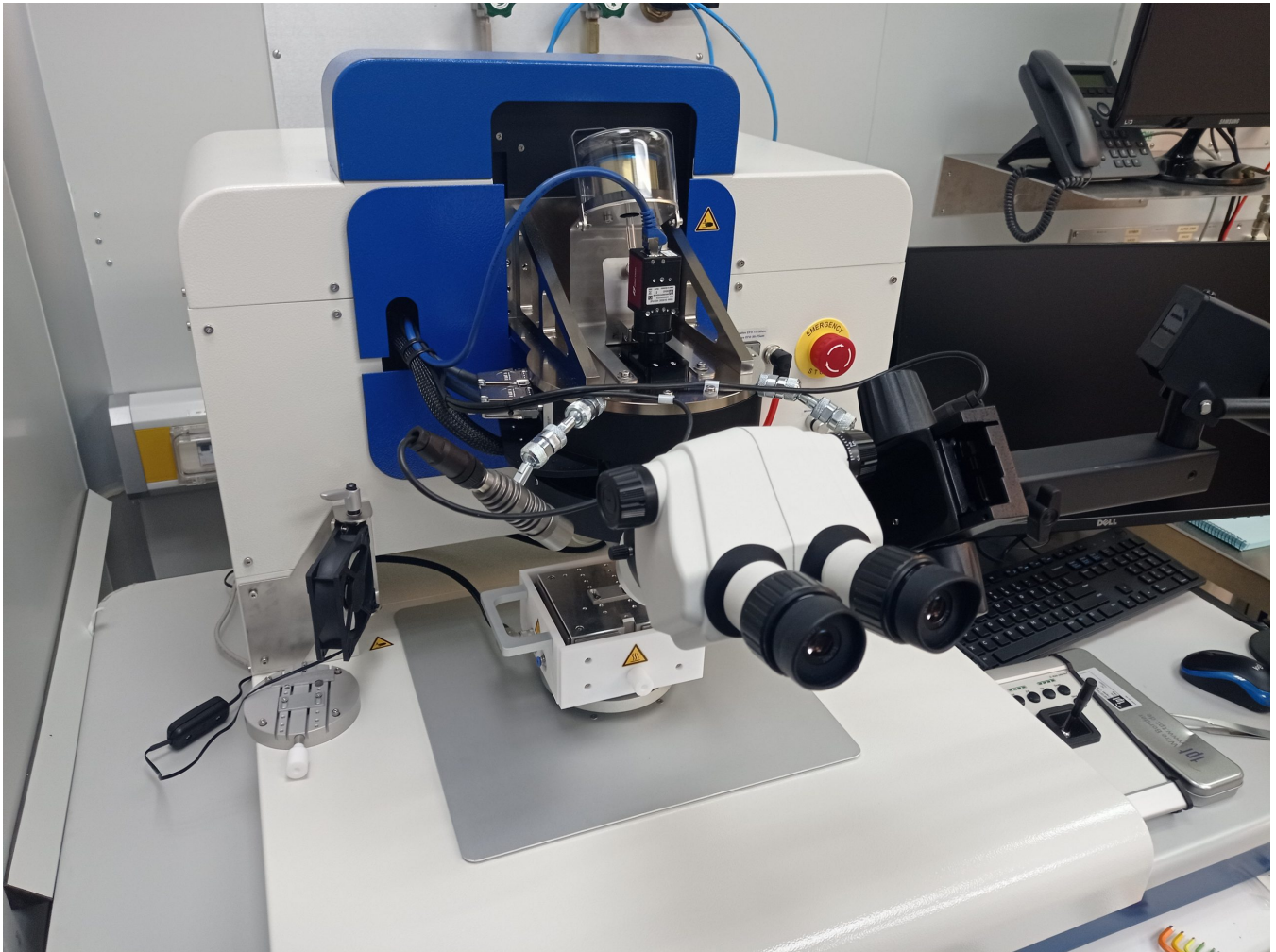


Electronic device soldering

TPT HB100 semi-automatic bonder



Contact information

Address: ISOM
ETSITelecomunicación
Avda. Complutense 30
28040 Madrid
Phone number: 910672593
Website: isom.upm.es
Email: manuel.abuin@iupm.es

Technological Offers type

Technological scientific services

Research and innovation areas

- Digital Technologies, Artificial Intelligence, Cybersecurity, 5G, Robotics
- Industry, Materials and Circular Economy
- Science For Engineering and Architecture

ODS



Available from: 2021

Where?

ISOM Semiconductor Devices Group University Optoelectronics and Microtechnology Systems Institute

Keywords: | bonding | Contact | welding

Electronic device soldering

TPT HB100 semi-automatic bonder

Description of the services offered

Making electrical connections with metal wires in different materials and with different micron in diameter. The contact can be made in the shape of a ball or flat.

Needs requested and applications

The equipment is used to join any kind of electronic device to any type of base or set of pads

Sector or area of application

Electronics and optoelectronics

Differential skills

Previous references for provision of services

Equipment description

ISOM. HTSE Telecommunications

Request for service

[Protocolo de Acceso](#)
